

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-18 (Canceled).

19. (Currently Amended) The ceramic film of claim ~~18~~26, wherein said dielectric constant is from 2.2 to 1.3.

20. (Currently Amended) The ceramic film of claim ~~18~~26, wherein a halide content is less than 500 ppb.

21. (Currently Amended) The ceramic film of claim ~~18~~26, wherein said metal content is less than 1 ppm.

22. (Currently Amended) The ceramic film of claim ~~18~~26, wherein said metal content is less than 100 ppb.

23. (Currently Amended) The ceramic film of claim ~~18~~26, having a porosity of about 40% to about 80%.

24. (Currently Amended) The ceramic film of claim ~~18~~26, having a porosity of about 55% to about 75%.

25. (Currently Amended) ~~The ceramic film of claim 18,~~ A ceramic film produced by a process comprising:

preparing a film-forming fluid comprising a ceramic precursor, a catalyst, a surfactant

and solvent(s);

depositing said film-forming fluid on said substrate; and

removing said solvent(s) from said film-forming fluid on said substrate to produce said ceramic film on said substrate,

wherein said ceramic film has a dielectric constant below 2.3, and a metal content of less than 500 ppm and wherein said film includes pores sufficiently ordered in a plane of the substrate that an X-ray diffraction pattern of said film shows a diffraction peak at a d spacing greater than about 44 Å.

26. (Currently Amended) ~~The ceramic film of claim 18,~~ A ceramic film produced by a process comprising:

preparing a film-forming fluid comprising a ceramic precursor, a catalyst, a surfactant and solvent(s);

depositing said film-forming fluid on said substrate; and

removing said solvent(s) from said film-forming fluid on said substrate to produce said ceramic film on said substrate,

wherein said ceramic film has a dielectric constant below 2.3, and a metal content of less than 500 ppm and wherein said film does not include pores sufficiently ordered in a plane of the substrate such that an X-ray diffraction pattern of said film shows a diffraction peak.

27. (Canceled)

28. (Currently Amended) The ceramic film of claim ~~27~~35, wherein said dielectric

constant is from 2.2 to 1.3.

29. (Currently Amended) The ceramic film of claim ~~27~~35, wherein a halide content is less than 500 ppb.

30. (Currently Amended) The ceramic film of claim ~~27~~35, wherein said metal content is less than 1 ppm.

31. (Currently Amended) The ceramic film of claim ~~27~~35, wherein said metal content is less than 100 ppb.

32. (Currently Amended) The ceramic film of claim ~~27~~35, having a porosity of about 50% to about 80%.

33. (Currently Amended) The ceramic film of claim ~~27~~35, having a porosity of about 55% to about 75%.

34. (Currently Amended) ~~The ceramic film of claim 27~~ A ceramic film having a dielectric constant below 2.3, a metal content of less than 500 ppm and a porosity of about 40% to about 80%., wherein said film includes pores sufficiently ordered in a plane of the substrate that an X-ray diffraction pattern of said film shows a diffraction peak at a d spacing greater than about 44 Å.

35. (Currently Amended) ~~The ceramic film of claim 27~~ A ceramic film having a dielectric constant below 2.3, a metal content of less than 500 ppm and a porosity of about 40% to about 80%., wherein said film does not include pores sufficiently ordered in a plane of the substrate such that an X-ray diffraction pattern of said film shows a diffraction peak.

36. (Currently Amended) The ceramic film of claim ~~27~~34, having a median pore size less than about 50Å.

37. (Currently Amended) The ceramic film of claim ~~23~~35, having a median pore size less than about 50Å.